## In the Claims:

- 1. (currently amended) A light emitting device of a II-VI
  group compound semiconductor formed on a compound
  semiconductor substrate and having an active layer between
  an n-type cladding layer and a p-type cladding layer,
  comprising
- [[a]] an i-type semiconductor barrier layer having a
  band gap larger than a band gap of said p-type cladding
  layer, provided between said active layer and said p-type
  cladding layer.
- (withdrawn) The semiconductor light emitting device
   according to claim 1, wherein
- said light emitting device of the II-VI group compound is a ZnSe based light emitting device;
- said n-type cladding layer is an n-type  $Zn_{1-x}Mg_xS_ySe_{1-y}$ 6 (0 < x < 1, 0 < y < 1) layer; and
- said p-type cladding layer is a p-type  $Zn_{1-x}Mg_xS_ySe_{1-y}$ 8 (0 < x < 1, 0 < y < 1) layer.
- 3. (original) The semiconductor light emitting device
   according to claim 1, wherein
- magnitude of the band gap of said barrier layer is larger by 0.025 eV to 0.5 eV than the band gap of said p-type cladding layer.

- 1 4. (previously presented) The semiconductor light emitting
  2 device according to claim 1, wherein
- in the band gap of said barrier layer, energy of

  valence band is approximately the same as or higher than

  that of said p-type cladding layer, and energy of

  conductive band is larger than that of said p-type cladding

  layer.
- (original) The semiconductor light emitting device
   according to claim 1, wherein
- said barrier layer is of a II-VI group compound semiconductor containing Be.
- 6. (original) The semiconductor light emitting device
   according to claim 5, wherein
- said barrier layer is of  $Zn_{1-x-y}Mg_xBe_ySe$  (0  $\leq$  x + y  $\leq$  1, 0 < x, 0 < y).
- 7. (withdrawn) The semiconductor light emitting device according to claim 1, wherein
- said barrier layer is of  $Zn_{1-x}Mg_xS_ySe_{1-y}$ .
- 1 **8.** (withdrawn) The semiconductor light emitting device according to claim 1, comprising
- a semiconductor trap layer having a band gap smaller
  than a band gap of said p-type cladding layer, provided
  between said barrier layer and said p-type cladding layer.

- 9. (withdrawn) The semiconductor light emitting device according to claim 8, having a multi-stacked structure in which a plurality of double-layer-structure of said barrier layer and said trap layer are stacked.
- 1 10. (withdrawn) The semiconductor light emitting device according to claim 8, wherein
- said trap layer is of  $ZnS_xSe_{1-x}$  (0  $\leq x \leq 0.1$ ).
- 1 11. (original) The semiconductor light emitting device according to claim 1, wherein
- said p-type cladding layer is formed of  $(Zn_{1-x}Cd_xS)_{1-z}(MgS_{1-y}Se_y)_z \text{ (where } x,\ y,\ z \text{ satisfy } 0 < x \le 1, \\ 0 \le y \le 1,\ 0 \le z < 1).$
- 1 12. (original) The semiconductor light emitting device
  2 according to claim 1, wherein
- thickness of said barrier layer is at least 5 nm and at most thickness of said active layer.
- 1 13. (original) The semiconductor light emitting device according to claim 1, wherein
- an n-type ZnSe single crystal substrate is used as said compound semiconductor substrate.
- 1 14. (original) The semiconductor light emitting device 2 according to claim 1, wherein

- an n-type GaAs single crystal substrate is used as said compound semiconductor substrate.
- 1 15. (original) The semiconductor light emitting device according to claim 1, wherein

in a stacked structure including said compound semiconductor substrate constituting said ZnSe based light emitting device, deviation between a peak of X-ray diffraction of a plane orientation used as an index of distortion from said substrate and a peak of X-ray diffraction of said plane orientation from said stacked structure is at most 1000 seconds.

## Claims 16 to 22 (cancelled).

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- 1 23. (new) The semiconductor light emitting device according to
  2 claim 1, wherein said barrier layer is a single monolayer
  3 interposed between said active layer and said p-type
  4 cladding layer.
- 1 24. (new) The semiconductor light emitting device according to claim 1, wherein said barrier layer is disposed directly on said active layer.
- 1 **25.** (new) The semiconductor light emitting device according to claim 1, wherein said p-type cladding layer is disposed directly on said barrier layer.